

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
262-253-5900 FAX 262-253-5919

DESCRIPTION:

Resinlab™ EP1300 Clear is a two part unfilled electronic grade epoxy encapsulant designed for small to medium sized castings. It has a pot life of about one hour and cures quickly to a tack free handle strength at room temperature within 3 to 4 hours reaching a tough, semi-rigid state within 48 hours. Cure can be accelerated by the addition of heat. Times and temperatures from 30 minutes at 100 °C to 1 hour at 80 °C or 4 hours at 50 °C will bring the product to full cure.

EP1300 Clear has good wetting and adhesion to most surfaces and is free flowing to penetrate voids and give good air release. It has very good resistance to water, acids and bases and most organic solvents.

TYPICAL PROPERTIES:

All properties given are at 25 °C unless otherwise noted.

Property:	Value:	Test Method or Source:
Color	Clear	Visual
Mix Ratio	Part A to Part B	Calculated
By weight	1.15 to 1	
By volume	1 to 1	
Cure Schedule	4 hours @ 50 °C 1 hour @80 °C 30 minutes @ 100 °C	
Viscosity – Part A	12,000 cps	Rheometer parallel plate 25mm@1/s
Viscosity – Part B	7,000 cps	455300006291
Viscosity - Mixed	7,300 cps	
Specific Gravity – Part A	1.16	Calculated
Specific Gravity – Part B	0.96	
Specific Gravity - Mixed	1.05	
Pot Life, defined as the time it takes for initial mixed viscosity to double	20 minutes	Rheometer parallel plate 25mm@1/s 455300006291
Gel Time	33 minutes /100cc sample	455300005339/Gardco Hot Pot Gel Timer
Glass Transition Temperature/Tg	40 °C	453560822409 by DSC
Hardness	80 Shore D	455300006287/ASTM D2240
Water Absorption	0.06% after 24 hours	457561824543/ASTM D570
Peak Exotherm	41.5 °C after 62 minutes for 40mL sample	455300005593 by Type K thermocouple
Tensile Properties:		455300006285/ASTM D638
Strength	4,500 psi	
Elongation	10%	
Modulus	200,000 psi	
Lap Shear Strength		4535601224468/ASTM D1002
0.010" bond line Al to Al	1,100 psi	
Compressive Properties:		455300006265/ASTM D695
Strength	20,000 psi	
Modulus	98,000 psi	
Flame Resistance	Passes Resinlab testing with HB rating at 6.0mm thickness. Not UL Certified.	UL94

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Thermal Conductivity by LFA	<0.2 W / (m.K)*	453560822409/ASTM E1461
Surface Resistivity	3.9 x 10 ¹⁶ ohm/sq (@ 44 %RH)	455300006612/ASTM D257
Volume Resistivity	6.8 x 10 ¹⁵ ohm-cm (@ 19 °C)	
Dielectric Constant / Dissipation Factor		455300006513/ASTM D150
@ 100 Hz	3.4, 0.027	
@ 100 kHz	3.0, 0.019	
Dielectric Strength	850 V/mil*	ASTM D149 Method A, immersed in ASTM D3487 Type II Oil
Coefficient of Thermal Expansion by TMA	54 ppm/ °C below Tg 196 ppm/ °C above Tg	455300005340/ASTM E831 TMA, 5 °C/min
Temperature Rating	-40 to 150 °C**	

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.

** Temperature Rating is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.

*** This TDS contains values that have been updated. The values reported in this technical data sheet are typical values of the product, and are highly dependent on test conditions and methodology. We actively seek the most precise and accurate ways to measure and interpret performance of our products, and to update estimated values with measured values. The formula has not been revised or changed in any way. Although the values on paper have changed, you can expect the same performance of the product.

INSTRUCTIONS:

1. Bring both components to room temperature prior to mixing.
2. Cartridge format: Mixer should be attached keeping the cartridge vertical and any air pocket purged this way. After the mixer contains material, the mixer tip can be dropped to dispense pre-bleed amount. Attach a new static mixer with each cartridge, then pre-bleed the first 3 inches of dispensed material or until a uniform color is obtained. Maintain adequate velocity during dispensing to ensure complete mixing.
3. Bulk format: weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on the surface of the casting. Maintain adequate velocity during dispensing to ensure complete mixing.
4. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.
5. Clean up uncured resin with suitable organic solvent such as MEK, acetone or other organic solvent.

SHELF LIFE AND STORAGE: 12 months at 25 °C
Specialty packaging may be less.

Many epoxy resin systems are prone to crystallization as epoxy resin is a super-cooled fluid. This condition may give the product a gritty or grainy appearance (or hazy in clear products). Products in this state will not usually cure to normal and expected properties. In extreme cases it may appear solid and cured. Fluctuating temperatures (within 5 to 50 °C) aggravate this phenomenon. Heating the individual component to 50 to 60 °C while stirring can usually restore products to original state. Storage at 25 +/- 10 °C is optimum for most products.